

Generic Specification: Printed boards

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EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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| <p>Käesolev Eesti standard EVS-EN 123000:2003 sisaldab Euroopa standardi EN 123000:1991+A1:1995+A2:1996 ingliskeelset teksti.</p> <p>Käesolev dokument on jõustatud 05.02.2003 ja selle kohta on avaldatud teade Eesti standardiorganisatsiooni ametlikus väljaandes.</p> <p>Standard on kättesaadav Eesti standardiorganisatsioonist.</p> | <p>This Estonian standard EVS-EN 123000:2003 consists of the English text of the European standard EN 123000:1991+A1:1995+A2:1996.</p> <p>This document is endorsed on 05.02.2003 with the notification being published in the official publication of the Estonian national standardisation organisation.</p> <p>The standard is available from Estonian standardisation organisation.</p> |
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| <p>Käsitlusala:</p> <p>This document is a Generic Specification (GS) applying to printed boards within the CENELEC system for Electronic Components of Assessed Quality. It relates to printed boards irrespective of their method of manufacture, when ready for mounting of the components.*</p> | <p>Scope:</p> <p>This document is a Generic Specification (GS) applying to printed boards within the CENELEC system for Electronic Components of Assessed Quality. It relates to printed boards irrespective of their method of manufacture, when ready for mounting of the components.*</p> |
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Võtmesõnad: approval, capability, generic specification, preparation of detail specifications, printed boards, quality conformance inspection

UDC:

Descriptors: Quality, electronic components, printed boards

English version

Generic Specification:

Printed boards

Spécification Générique:
Cartes imprimées

Fachgrundspezifikation:
Leiterplatten

This European Standard was approved by the CENELEC Electronic Components Committee (CECC) on 18 April 1991. The text of this standard consists of the text of CECC 23 000 Issue 1 1985 of the corresponding CECC Specification. CENELEC members are bound to comply with CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the General Secretariat of the CECC or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CECC General Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland, and United Kingdom. The membership of the CECC is identical, with the exception of the national electrotechnical committees of Greece, Iceland and Luxembourg.

CECC

CENELEC Electronic Components Committee
Comité des Composants Electroniques du CENELEC
CENELEC Komitee für Bauelemente der Elektronik

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FOREWORD

The CENELEC Electronic Components Committee (CECC) is composed of those member countries of the European Committee for Electrotechnical Standardization (CENELEC) who wish to take part in a harmonized System for electronic components of assessed quality.

The object of the System is to facilitate international trade by the harmonization of the specifications and quality assessment procedures for electronic components, and by the grant of an internationally recognized Mark, or Certificate, of Conformity. The components produced under the System are thereby accepted by all member countries without further testing.

The specification has been formally approved by the CECC, and has been prepared for those countries taking part in the System who wish to issue national harmonized GENERIC SPECIFICATIONS for PRINTED BOARDS. It should be read in conjunction with the current regulations for the CECC System.

At the date of printing of this specification the member countries of the CECC are Austria, Belgium, Denmark, Finland, France, Germany, Ireland, Italy, the Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and the United Kingdom, and copies of it can be obtained from the addresses shown on the blue fly sheet.

PREFACE

This generic specification was prepared by CECC Working Group 23: Printed Circuits.

It is based on the publications of the International Electrotechnical Commission (IEC).

The text of this specification was circulated to the CECC for voting in the documents indicated below and was ratified by the President of the CECC for printing as a CECC Specification.

| <u>Document</u> | <u>Voting date</u> | <u>Report on the Voting</u> |
|-----------------------|--------------------|-----------------------------|
| CECC(Secretariat)1003 | February 1981 | CECC(Secretariat)1210 |
| CECC(Secretariat)1507 | March 1984 | CECC(Secretariat)1579 |

SECRETARIAT NOTE:

DUE TO THE URGENT INDUSTRIAL NEED FOR THIS SPECIFICATION, THE PRESIDENT OF THE CECC HAS RULED THAT IT BE PUBLISHED WITHOUT THE FULL EDITORIAL PROCEDURE BEING APPLIED. USERS OF THE SPECIFICATION ARE ASKED TO REPORT TO THE CECC GENERAL SECRETARIAT ANY ERRORS THEY FIND SO THAT AMENDING ACTION CAN BE INITIATED.

The text is published initially in English and German. The French version will follow as soon as it has been prepared.

1. General

1.1 Scope

This document is a Generic Specification (GS) applying to printed boards within the CENELEC system for Electronic Components of Assessed Quality. It relates to printed boards irrespective of their method of manufacture, when they are ready for mounting of the components.

1.2 Object

To define system and procedure for approval of manufacturers and products and to provide rules for the preparation of specifications for printed boards.

1.3 Related documents

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| IEC 194 | Terms and definitions for printed boards |
| IEC 249 | Metal-clad base materials for printed boards |
| IEC 326-2 | Printed circuits - Test methods |
| IEC 410 | Sampling plans and procedures for inspection by attributes |
| CECC 00 007 | Sampling plans and procedures for inspection by attributes |
| CECC 00 010 | Printed boards - Test methods |

1.4 General considerations

Printed boards differ from most other electronic components in important factors, such as

- there are no standard boards with standard patterns and dimensions but an infinite variety of shapes and circuit configurations,
- they are "custom tailored", i.e. all details for a particular board must be agreed between customer and manufacturer,
- although they are made in considerable total quantities, the production quantity of a particular printed board may be small.

Therefore, the CECC Qualification Approval Procedure as detailed in CECC 00 107 Part I cannot be applied. Instead of this, it is necessary to use the CECC Capability Approval Procedure as laid down in CECC 00 107 Part III.

In case of printed boards capability approval is based on the use of composite test patterns as capability qualifying components with an appropriate selection of test methods and requirements for each type of printed board, e.g.

- single/double sided, with plain holes
- single/double sided, with plated-through holes